PCN Number: 201		0161027001 <mark>A</mark>		PCN I	PCN Date:		Nov 30, 2016		
Title:	Transfer of se	elect (C10 d	devices from ANAM	-1 to DM	10S5 W	/afer	Fab	site
Customer	Contact:		PCN	l Manager		Dept:			Quality Services
Proposed 1 st Ship Date:		:	Feb 28, 2017		Estimated Sample Availability:		le	Date provided at sample request.	
Change Type:									
Assembly Site			Assembly Process			Assembly Materials		sembly Materials	
Design			Electrical Specification				Mechanical Specification		
Test Site			Packing/Shipping/Labeling		J		Test Process		
☐ Wafer Bump Site		Wafer Bump Material				Wafer Bump Process			
		Wafer Fab Materials				Wa	ifer Fab Process		
			Part number change						
DON B. L. II									

PCN Details

Description of Change:

The purpose of this Rev A PCN is to add additional devices to the product affected section of this document. Additional devices are shown as bold with a yellow highlight.

This change notification is to announce the transfer of select devices from ANAM-1 to the DMOS5 Wafer Fab site. Fab support from ANAM-1 is being discontinued for the products listed in the product affected section of this document. Production at ANAM-1 will stop on February 28, 2017. Customers are advised to place their orders immediately to ensure fulfillment. Any orders placed after this date will be supported with DMOS5 material.

Curre	ent (Discontini	ued)	New (Transfer to Location)			
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter	
ANAM-1	C10	200mm	DMOS5	C10	200mm	

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
ANAM-1	ANM	KOR	Bucheon-si

New:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHD (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:	Product Affected:						
CDCLVD110ARHBR	CDCV304PW	TLK2201BIRCPRG4	TUSB2046BIRHBRG4				
CDCLVD110ARHBRG4	CDCV304PWG4	TLK2201BRCP	TUSB2046BIRHBT				
CDCLVD110ARHBT	CDCV304PWR	TLK2201BRCPG4	TUSB2046BIRHBTG4				
CDCLVD110ARHBTG4	CDCV304PWRG4	TLK2201BRCPR	TUSB2046BVF				
CDCLVD110AVF	TLK2201BIRCP	TLK2201BRCPRG4	TUSB2046BVFG4				
CDCLVD110AVFG4	TLK2201BIRCPG4	TUSB2046BIRHB	TUSB2046BVFR				
CDCLVD110AVFR	TLK2201BIRCPR	TUSB2046BIRHBR	TUSB2046BVFRG4				
CDCLVD110AVFRG4							

Qualification Report

CDCV304: Qualification of alternative FAB (DMOS5)

Approve Date 04-Dec-2015

Product Attributes

Attributes		QBS Product Reference CDCV304	QBS Process Reference: SN74AVC16T245DGGR	QBS Package Reference: CDCVF2505PW	QBS Package Reference: LMV324IPWR	QBS Package Reference: RC4558PWR	QBS Package Reference: SN0508073PW
Wafer Fab Supplier	DMOS5	DMOS5	CFAB	ANAM-1	FFAB	SFAB	MLA
Wafer Process	33C10	33C10	33C10	33C10	BCB	JI-SLM	LBC4X
Assembly Site	MLA	MLA	MLA	MLA	ASE SHANGHAI	MLA (TIM)	MLA
Package Family	TSSOP	TSSOP	TSSOP	TSSOP	TSSOP	TSSOP	TSSOP

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: CDCV304	QBS Product Reference CDCV304	QBS Process Reference: SN74AVC16T245D GGR	QBS Package Reference: CDCVF2505PW	QBS Package Reference: LMV324IPWR	QBS Package Reference: RC4558PWR	QBS Package Reference: SN0508073PW
AC	Autoclave 121C	96 Hours	-	1/77/0	3/231/0	3/231/0	-	1/77/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	2/154/0	1/77/0	-
HAST	Biased HAST, 130C/85%RH	192 Hours					2/154/0		
HBM	ESD - HBM	2500 V	1/3/0	1/3/0	3/9/0	-	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	3/9/0	-	-	-	-
HTSL	High Temp. StorageBake, 150C	1000 Hours	-		-	-	-	-	-
HTSL	High Temp. StorageBake, 170C	420 Hours	-		3/231/0	3/231/0	1/77/0	-	3/231/0
HTOL	High Temp Operating Life, 150C	300 Hours			3/231/0	-	-	-	-
LU	Latch-up	(per JESD78)	1/6/0		3/18/0	-	-	-	-
TC	Temperature Cycle, -55/125C	700 Cycles	-		-	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	-	1/77/0	3/231/0
TS	Thermal Shock, -65/150C	500 Cycles	-		-	3/231/0	-	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-		-	-	1/77/0	-	-
WBP	Bond Strength	Wires	-		3/228/0	-	2/154/0	1/76/0	-
MQ	Manufacturability	(per mfg. Site specification)	Pass	Pass					

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

QBS: Qual By Similarity
 Qual Device CDCV304 is qualified at LEVEL1-260C

Qualification Report

TUSB2046B in DMOS5 (C10 offload from Dongbu to DMOS5) Approve Date 15-Nov-2016

Product Attributes

Attributes	Qual Device: TUSB2046BIRHB	Qual Device: TUSB2046BVF	QBS Process Reference: TLK2500IRCP
Assembly Site	MLA	PHI	PHI
Package Family	QFN	LQFP	HTQFP
Wafer Fab Supplier	DMOS5	DMOS5	DMOS5
Wafer Fab Process	33C10	33C10	25C10

- QBS: Qual By Similarity
- Qual Device TUSB2046BIRHB is qualified at LEVEL2-260C
- Qual Device TUSB2046BVF is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TUSB2046BIRHB	Qual Device: TUSB2046BVF	QBS Process Reference: TLK2500IRCP
AC	Autoclave 121C	96 Hours	-	-	3/231/0
CDM	ESD - CDM	1500 V	-	1/3/0	-
ED	Electrical Characterization	Per Data Sheet Parameters	-	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	4000 V	-	1/3/0	-
HTOL	Life Test, 155C	240 Hours	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/135/0
LU	Latch-up	(Per JESD78)	-	1/6/0	-
TS	Thermal Shock -65/150C	500 Cycles	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	-
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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